Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	10 X 10 X 0.85 (6.75 EP)
Lead Count	84
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.85E-02	86.9	869100	32.39	323858
Thermosets	Epoxy & Phenol Resin	Proprietary	1.30E-02	12.8	127800	4.76	47623
Other inorganic materials	Carbon black	1333-86-4	3.16E-04	0.3	3100	0.12	1155
Subtotal			1.02 E-01	100.00	1000000	37.26	372636

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.31 E-01	96.37	963700	47.97	479705
Copper & its alloys	Nickel	7440-02-0	3.40 E-03	2.50	25000	1.24	12444
Copper & its alloys	Silicon	7440-21-3	8.16 E-04	0.60	6000	0.30	2987
Copper & its alloys	Zinc	7440-66-6	6.80 E-04	0.50	5000	0.25	2489
Copper & its alloys	Silver	7440-22-4	4.08 E-05	0.03	300	0.01	149
Subtotal			1.36 E-01	100.00	1000000	49.78	497775

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.96 E-04	100.0	1000000	0.22	2181

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.59 E-03	100.0	1000000	1.68	16800

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.64 E-03	100.0	1000000	1.33	13323

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.54 E-02	100.0	1000000	9.28	92784

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Epoxy Resin	Proprietary	8.12 E-04	66.00	660000	0.30	2971
Others	Polymeric Resin	Proprietary	4.18 E-04	34.00	340000	0.15	1531
Subtotal			1.23 E-03	100.0	1000000	0.45	4502

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.73 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary